

# **International Conference on Soldering and Reliability 2011**

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at the address below.

Surface Mount Technology Association (SMTA)  
5200 Wilson Road  
Suite 215  
Edina, MN 55424

Phone: (952) 920-4682  
Fax: (952) 926-1819

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# International Conference on Soldering & Reliability

## May 3 – 6, 2011

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